

ABSTRACT

METHOD OF MANUFACTURING MULTI-LEVEL SILICON
MICROMECHANICAL PARTS AND PARTS THEREBY
OBTAINED

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The process comprises the following steps :

a) a first element (3) or a plurality of said first elements (3) is/are
machined in a first silicon wafer (1) keeping said elements (3) joined
10 together via material bridges (5);

b) step a) is repeated with a second silicon wafer (2) in order to
machine a second element (4), differing in shape from that of the first
element (3), or a plurality of said second elements (4);

c) the first and second elements (3, 4) or the first and second wafers
15 (1, 2) are applied, face to face, with the aid of positioning means (6, 7);

d) the assembly formed in step c) undergoes oxidation; and

e) the parts (10) are separated from the wafers (1, 2).
Micromechanical timepiece parts obtained according to the process.

20 Figure 1